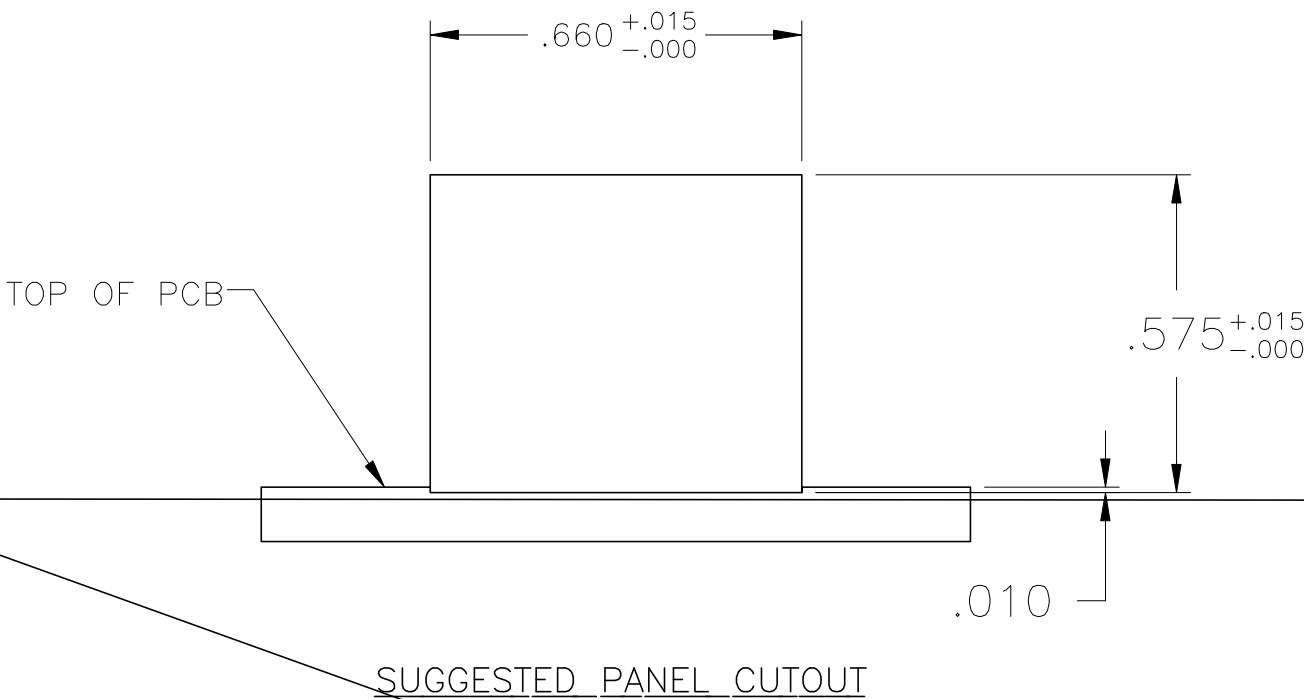
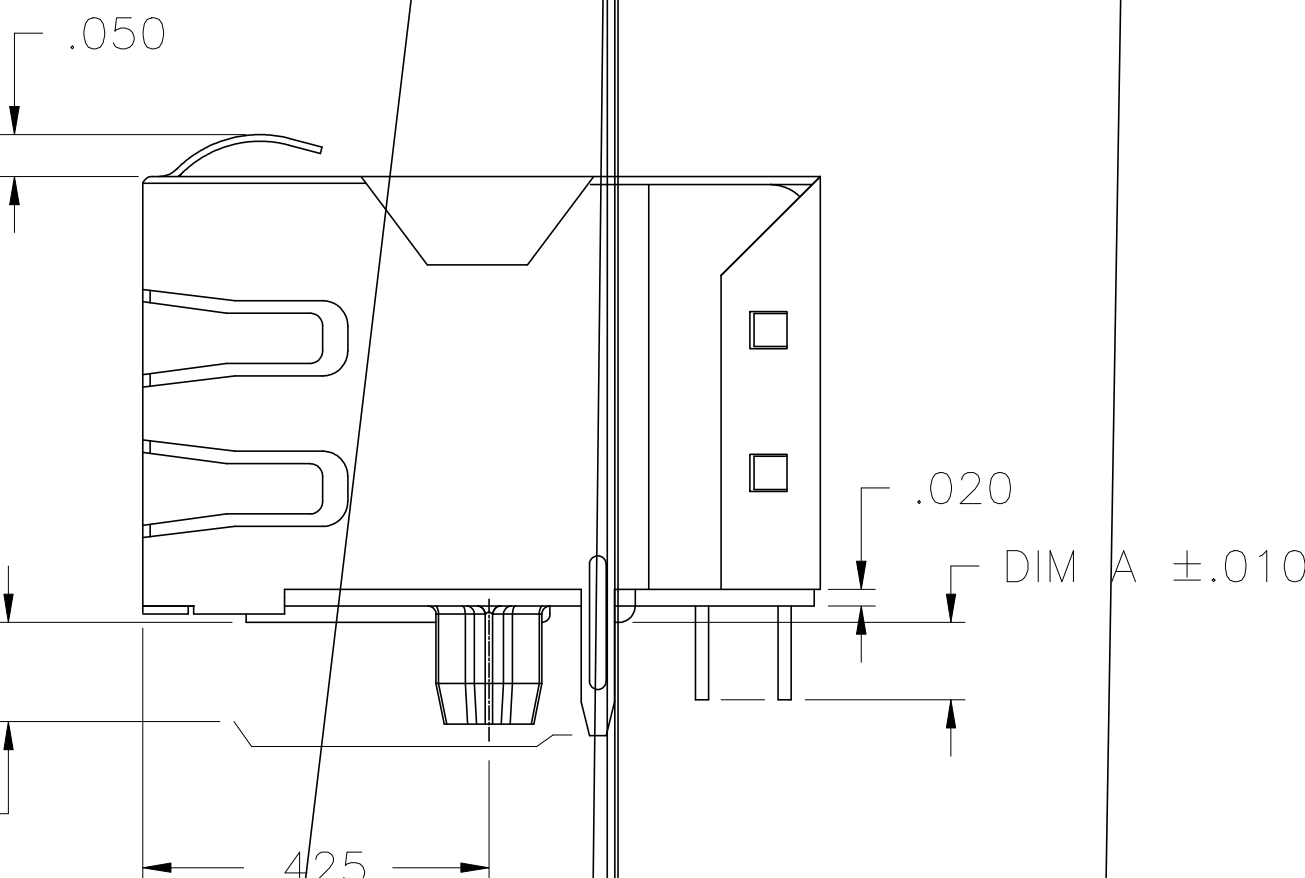
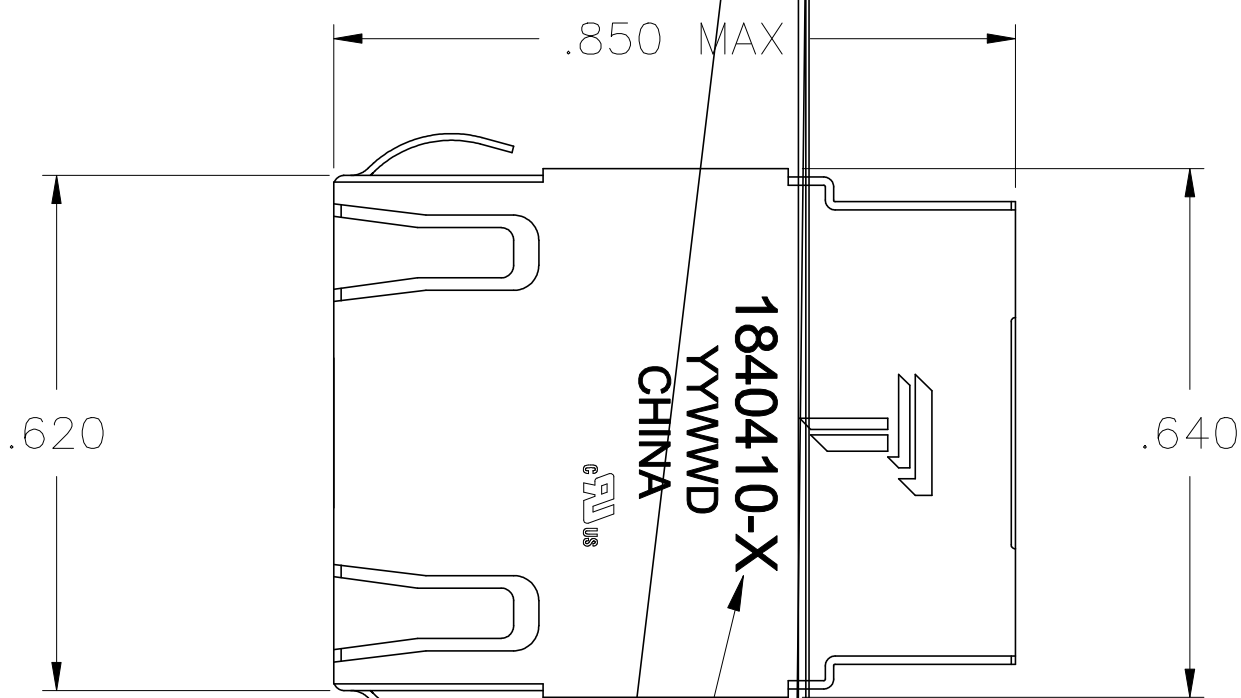
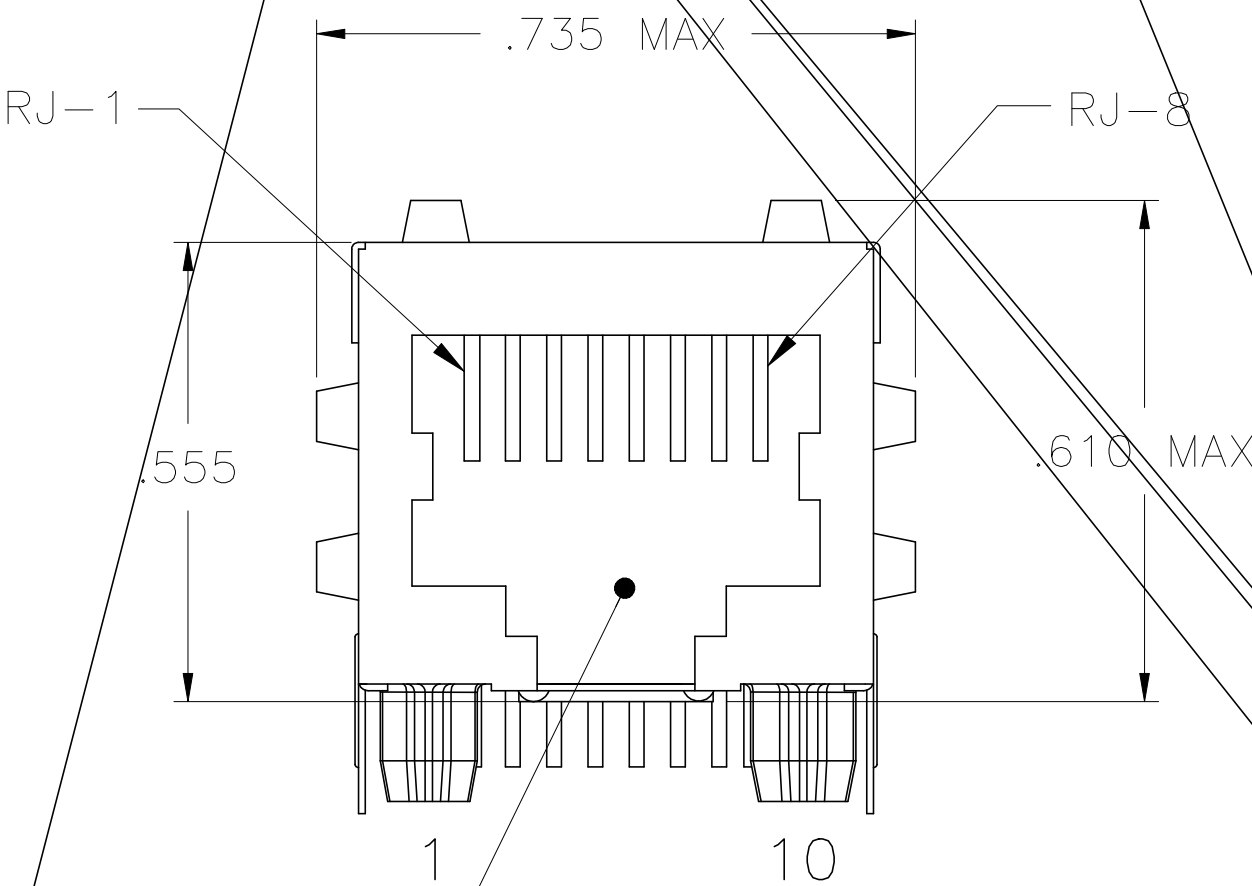
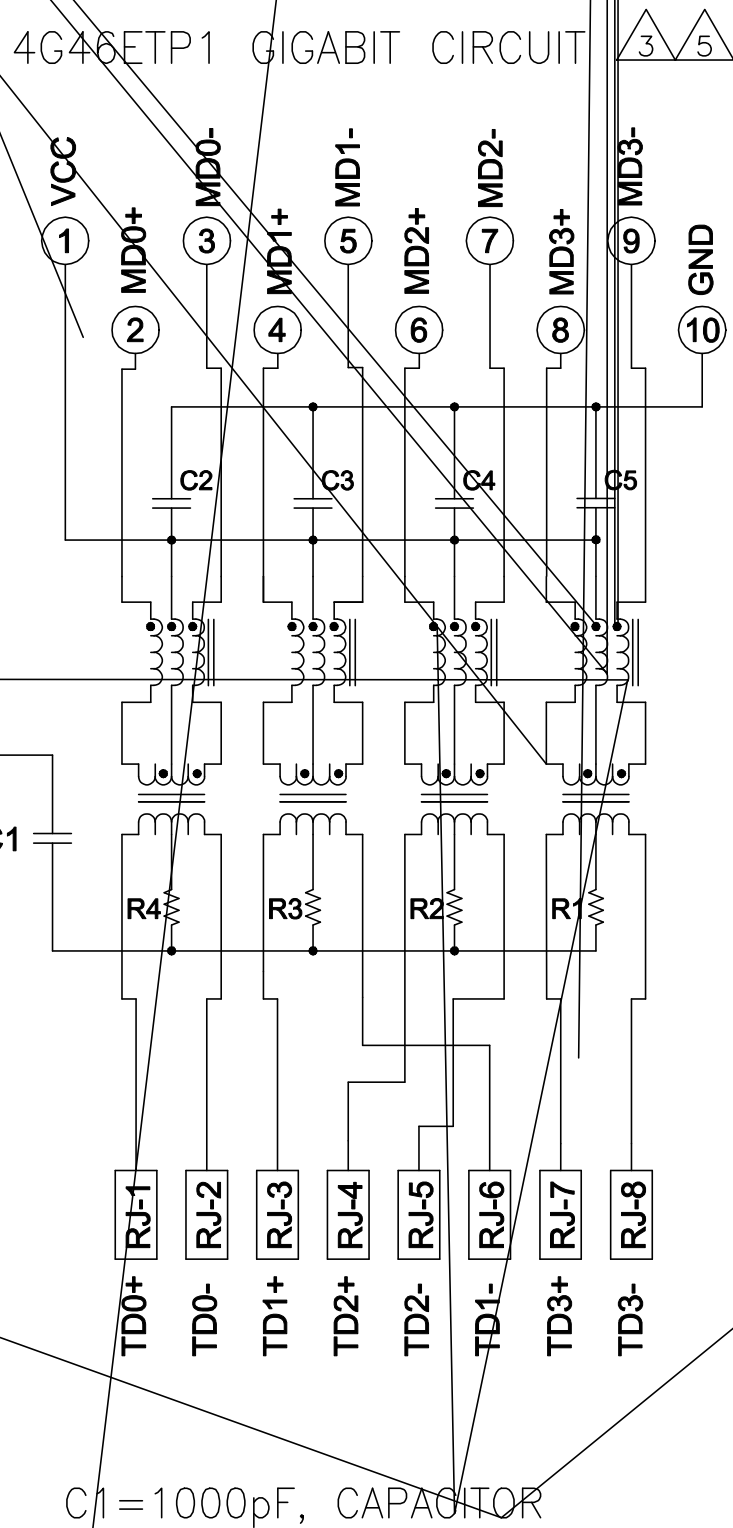


MECHANICAL:



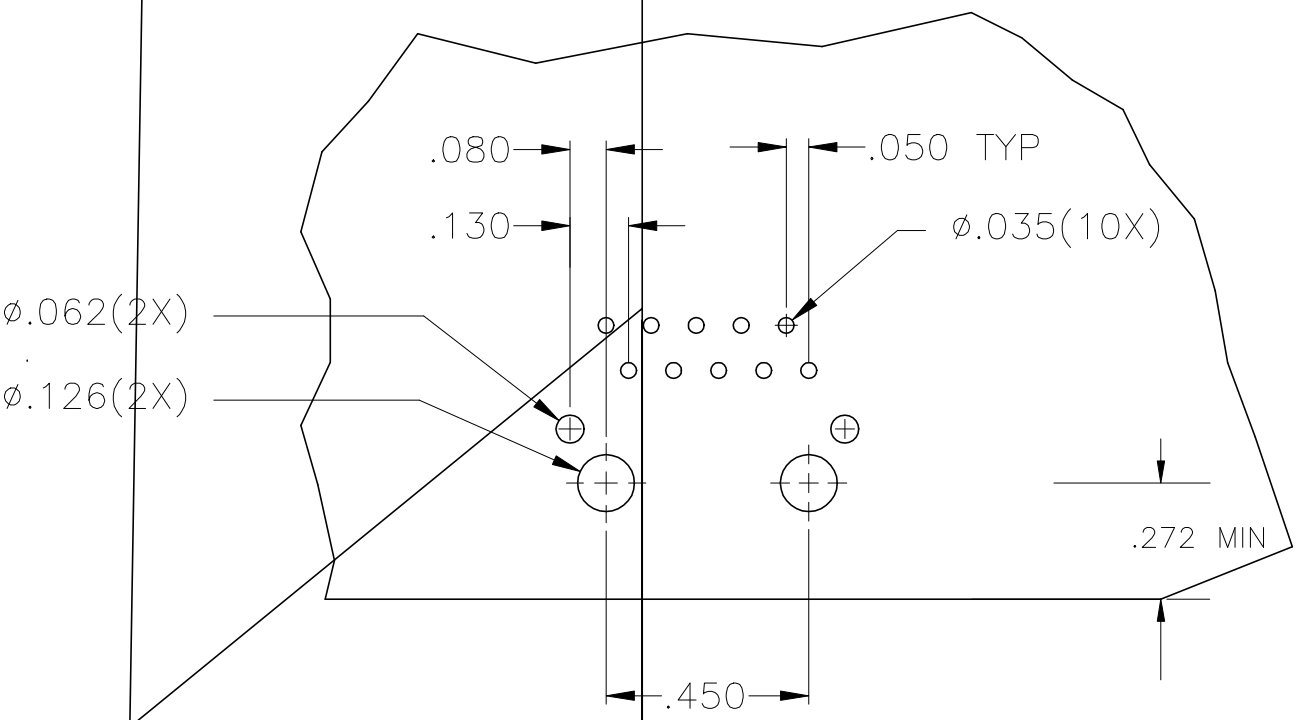
ELECTRICAL:



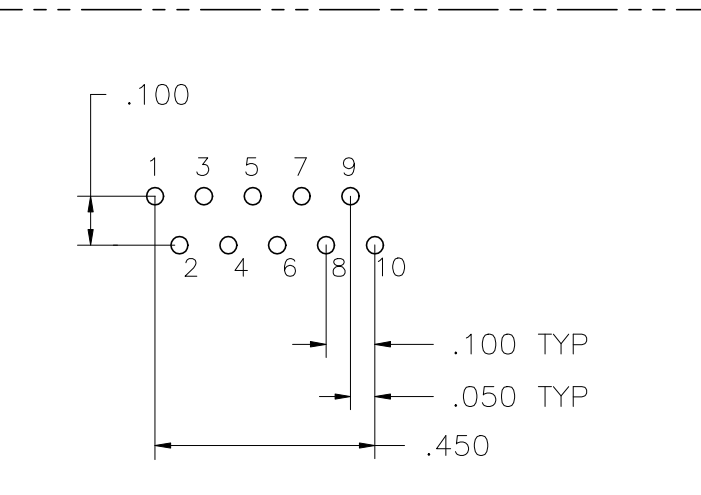
C1=1000pF, CAPACITOR

NOTES:

1. MATERIALS
 - HOUSING: THERMOPLASTIC, FLAMMABILITY RATING UL 94V-0.
 - SHIELD: BRASS C26800 0.008 INCH THICK, PREPLATED WITH 30μ INCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μ INCH MIN SAC SOLDER.
 - CONTACTS: PHOSPHOR BRONZE 0.0157 X 0.018", 50μ INCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECTIVE 50μ INCH MIN HARD GOLD FINISH PLATE.
 - SOLDER TAILS: 100μ INCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
2. RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 SUB PART F.
3. MAGNETICS
 - APPLICATION: 10/100/1000 BASE-T, EXTENDED TEMPERATURE
 - IMPEDANCE: 100 OHMS
 - TURNS RATIO (CHIP: CABLE): 1:1 ALL FOUR PAIRS
 - OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN. @100kHz, 0.1VRMS, 8mADC BIAS FROM -40°C TO +85°C, ALL FOUR PAIRS
 - ALL FOUR PAIRS BI-DIRECTIONAL
 - PERFORMANCE @ 25°C:
 - INSERTION LOSS (IL): 1.1dB MAX. FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz
 - 12-20LOG(f/80)dB MIN. FROM 40.1MHz TO 100MHz
 - CROSSTALK ATTENUATION: 35dB MIN. FROM 0.5MHz TO 40MHz
 - 33-20LOG(f/50)dB MIN. FROM 40.1MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN. FROM 0.5MHz TO 100MHz
 - ISOLATION VOLTAGE:
 - 1840410-1, 1840410-2 COMPLY WITH IEEE802.3 2002, PARA 40.6.1.1, ITEM b.
 - 1840410-6 COMPLIES WITH IEEE802.3 2002, PARA 40.6.1.1, ITEM a and b.
4. OPERATING TEMPERATURE: FROM -40°C TO +85°C.
5. INDICATED MAGNETIC CONNECTIONS ARE SYMMETRICAL TO SUPPORT AUTO-MDI/MDIX.
6. TRP CONNECTOR LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
7. THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.



SUGGESTED PCB LAYOUT
COMPONENT SIDE



PIN DESIGNATIONS